

N109 W13300 ELLSWORTH DRIVE GERMANTOWN, WI 53022
262-253-5900 FAX 262-253-5919

DESCRIPTION:

Resinlab® EP1026HP is a high performance fast setting epoxy adhesive designed for bonding metals, ceramics, glass and most plastics. This product will have good resistance to water, salt spray, inorganic acids and bases and most organic solvents.

EP1026HP will cure to full properties at room temperature within 24 hours. Significantly higher adhesion can be achieved by application of heat after the product has gelled. Time and temperature of 1 hour @ 100 °C is sufficient.

TYPICAL PROPERTIES:

All properties given are at 25 °C unless otherwise noted.

Property:	Value:	Test Method or Source:
Color	Off White	Visual
Mix Ratio	Part A to Part B	Calculated
Mix Ratio by weight	1 to 1	
Mix Ratio by volume	1.04 to 1	
Cure Schedule	24 hrs @ 25 °C 2 hrs @ 65 °C	
Viscosity - Part A	7,000 cP	TA HR20 Rheometer 25mm parallel plate @ 1/s DCV6100723
Viscosity - Part B	17,000 cP	
Viscosity - Mixed	12,500 cP *	
Specific Gravity - Part A	1.13	Calculated
Specific Gravity - Part B	1.13	
Specific Gravity - Mixed	1.13	
Gel Time 100cc Sample	5 minutes	455300005339/Gardco Gel Timer
Hardness	80 Shore D	455300006287/ASTM D2240
Glass Transition Temperature/Tg	22 °C	453560822409 by DSC
Water Absorption	1.7 %	24 hr immersion 457561824543/ASTM D570
Peak Exotherm	153 °C after 4 minutes for 50 mL sample	455300005593 by Type K thermocouple
Tensile Properties:		4535601224470/ASTM D638
Strength	3,500 psi	
Elongation	20 %	
Modulus	253,000 psi	
Lap Shear Strength		4535601224468/ASTM D1002
0.010" Bond Line, Al to Al	3,500 psi / see table below for more information	
T-Peel Strength	15 pli *	ASTM D1876

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Property:	Value:	Test Method or Source:
Compressive Properties:		4535601224467/ASTM D695
Yield Strength	4,000 psi	
Ultimate Strength	46,000 psi	
Modulus	200,000 psi	
Thermal Conductivity by LFA	0.23 W/m.K	453560822409/ASTM E1461
Volume Resistivity	8.65 x 10 ¹⁴ ohm-cm	455300006612/ASTM D257 @ 34 °C @ 53 %RH
Surface Resistivity	1.99 x 10 ¹⁵ ohm/sq	455300006612/ASTM D257 @ 34 °C @ 53 %RH
Dielectric Constant & Dissipation Factor		455300006513/ASTM D150
@ 100 Hz	4.0, 0.034	
@ 100 kHz	3.5, 0.037	
AC Dielectric Strength	48 kV/mm	DCV6101609; ASTM D149 Method A, immersed in ASTM D3487 Type II Oil
Coefficient of Thermal Expansion by TMA		455300005340/ASTM E831 TMA, 5 °C/min
below Tg	64 ppm/°C	
above Tg	220 ppm/°C	
Operating Temperature Range	-40 to 80 °C**	
Relative Thermal Index (RTI)	50 °C	UL746B, Table 7.1 Generic Value Based on Composition

* Asterisk denotes values considered typical to associated resin systems or extrapolated from other test results.

** Operating Temperature Range is based on average design requirements and is not intended as a guarantee of suitability for all applications operating at that temperature.

*** This TDS contains values that have been updated. The values reported in this technical data sheet are typical values of the product, and are highly dependent on test conditions and methodology. We actively seek the most precise and accurate ways to measure and interpret performance of our products, and to update estimated values with measured values. The formula has not been revised or changed in any way. Although the values on paper have changed, you can expect the same performance of the product.

Additional Performance Data – Lap Shear Adhesion, 4535601224468/ASTM D1002:

Substrate Type	Strength	Test Temperature	Cure Schedule	Bond Line Thickness
Al to Al	830 psi	25 °C	24 hr @ 25 °C	0.010 "
Al to Al	2,500 psi	25 °C	2 hrs @ 65 °C	0.010 "
Al to Al	3,500 psi	25 °C	2 hrs @ 100 °C	0.010 "

INSTRUCTIONS:

1. Bring to room temperature prior to use.

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2. Cartridge format: Mixer should be attached keeping the cartridge vertical and any air pocket purged this way. After the mixer contains material, the mixer tip can be dropped to dispense pre-bleed amount. Attach a new static mixer with each cartridge, then pre-bleed the first 3 inches of dispensed material or until a uniform color is obtained. Maintain adequate velocity during dispensing to ensure complete mixing.
3. Bulk format: stir until homogeneous weigh and mix parts A and B accurately and thoroughly, scraping sides of container often. Do not pour from mixing container, transfer to a new container as residual unmixed material may cause a tacky spot on the surface of the casting. Maintain adequate velocity during dispensing to ensure complete mixing.
4. Allow to cure undisturbed until product is fully gelled or tack-free to the touch.
5. Clean up uncured resin with suitable organic solvent such as MEK or acetone.

SHELF LIFE AND STORAGE:

12 months at 25 °C.
Specialty packaging may be less.

Many epoxy resin systems are prone to crystallization as epoxy resin is a super-cooled fluid. This condition may give the product a gritty or grainy appearance (or hazy in clear products). Products in this state will not usually cure to normal and expected properties. In extreme cases it may appear solid and cured. Fluctuating temperatures (within 5 to 50 °C) aggravate this phenomenon. Heating the individual component to 50 to 60 °C while stirring can usually restore products to original state. Storage at 25 +/- 10 °C is optimum for most products.